

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4439856	substrate board carrier pcb ((printed circuit wiring) adj4 board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 12:15
L2	4630990	wafer 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 12:16
L3	1626342	(plurality first second multi multiple adjacent) with (chip die semiconductor dice electronic ic (integrated adj (circuit circuitry)) component)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 12:17
L4	402592	2 same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 12:18
L5	1882654	(first second plurality stacked stacking stack stackable mount mounting mounted mountable) with (dielectric material pa polyarylene ether polyester phenolic polyimide polymide polysulfone polyether ether ketone polyurethane epoxy polyarylene ethers polyethylene terephthalate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 12:22
L6	84000	5 same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 12:22
L7	159919	4 and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 12:22

L8	334444	(first second plurality stacked stacking stack stackable mount mounting mounted mountable) with (pa polyarylene ether polyester phenolic polyimide polymide polysulfone polyether ether ketone polyurethane epoxy polyarylene ethers polyethylene terephthalate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 12:23
L9	7863	8 same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 12:23
L10	308	9 same (sio sios sic teos fteos fsg osg (silicon adj5 (nitride oxide)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/29 12:25